

MAR 3 1 2003

3/26/03

PATENT
Atty. Dkt. No. AMAT/1931.P1/CPI/COPPER/PJS

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:
Xi, et al.

Serial No.: 10/052,681

Confirmation No.: 4083

Filed: January 17, 2002

For: RELIABILITY BARRIER
INTEGRATION FOR CU
APPLICATION

Commissioner for Patents
Washington, D.C. 20231

Dear Sir:

Group Art Unit: 2814

Examiner: *Ginette Peralta* 4-4-03

CERTIFICATE OF MAILING
37 CFR 1.8

I hereby certify that this correspondence is being deposited on
3/26/03, 2003 with the United States Postal Service as
First Class Mail in an envelope addressed to: Commissioner
for Patents, Washington, D.C. 20231.

3/26/03

Kent R. Zabel

Date

Signature

RESPONSE TO RESTRICTION REQUIREMENT DATED FEBRUARY 26, 2003

In response to the Restriction Requirement dated February 26, 2003, having a shortened statutory period for response set to expire on March 26, 2003, please enter this response and reconsider the claims pending in the application for reasons discussed below. Although Applicant believes that no fee is due in connection with this response, the Commissioner is hereby authorized to charge counsel's Deposit Account No. 20-0782/AMAT/1931.P1/KMT, for any fees, including extension of time fees or excess claim fees, required to make this response timely and acceptable to the Office.

IN THE CLAIMS:

Please cancel claims 39-40 without prejudice.

1. A method of filling one or more of a via and a trench in a patterned substrate, comprising:

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